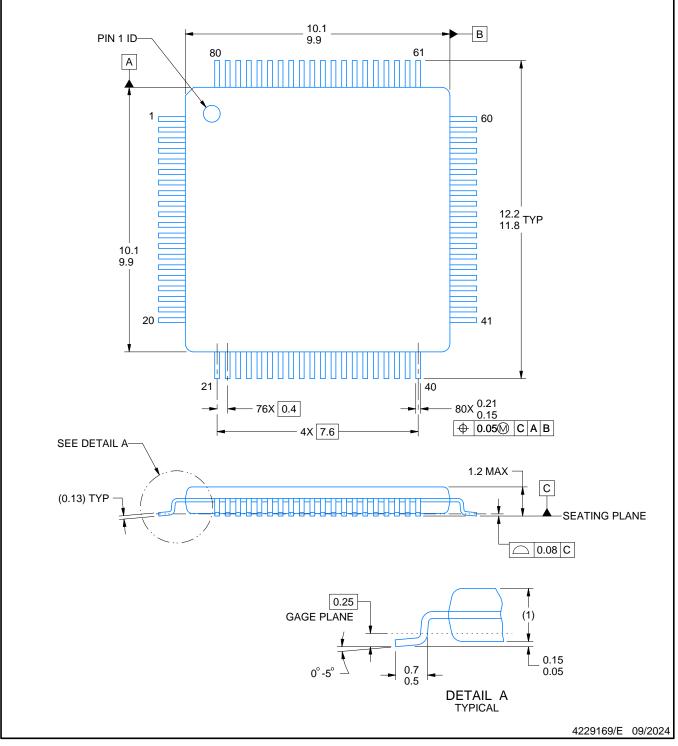
PNA0080A



PACKAGE OUTLINE

TQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing All lifear differsions are in minimeters, vary amore per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration MS-026.

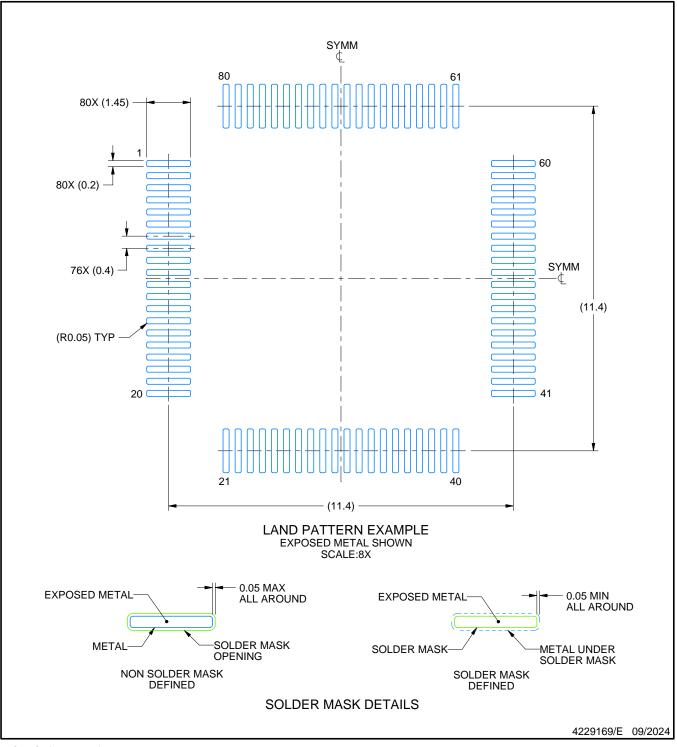


PNA0080A

EXAMPLE BOARD LAYOUT

TQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.

5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

6. For more information, see Texas Instruments literature number SLMA004 (www.ti.com/lit/slma004).

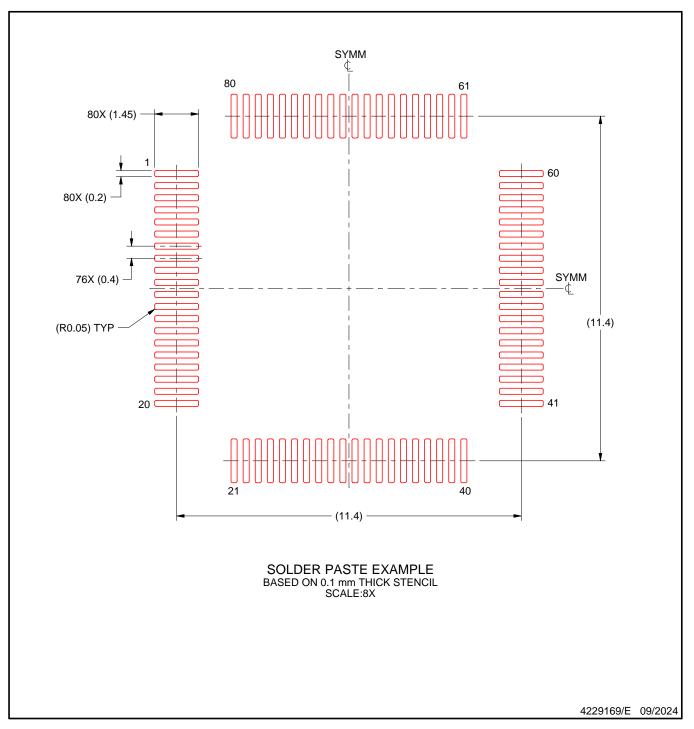


PNA0080A

EXAMPLE STENCIL DESIGN

TQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



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